

Recommended soldering conditions of EOREX Pb-Free products

- 1 Surface Mount Type (SMD) IR reflow with a peak temperature of 260°C Wave soldering with molten solder in a 260°C soldering bath Partial lead heating via a 350°C solder iron tip
- 2 Through Hole Type (THD) Wave soldering with molten solder in a 260°C soldering bath

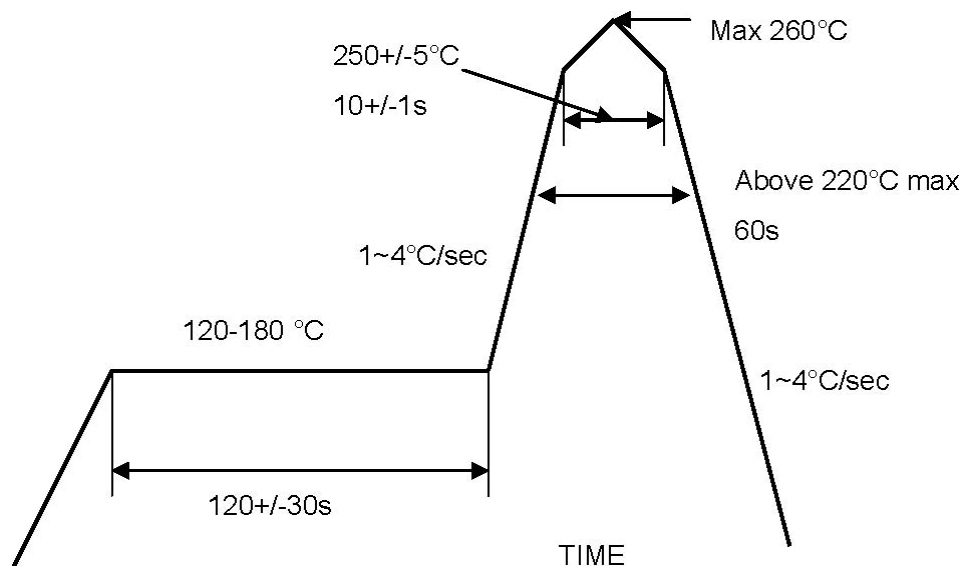
Partial lead heating via a 350°C solder iron tip 3. Hand Soldering Type Partial lead heating via a 350°C solder iron tip

IR Reflow

- Max. temperature (package surface temperature): 260°C
- Soldering time at maximum temperature: Within 10 seconds
- Soldering time at over 220°C: Within 60 seconds
- Preheating time at 120°C - 180°C: 120 ± 30 seconds
- Maximum number of reflows: 3
- Chlorine composition of rosin flux (%): 0.2% (wt.) or less

IR-Reflow Profile (Pb-free SMD)

Allowable upper limit IR reflow conditions for mounting Eorex Pb-free surface mounted devices:



Wave Soldering

- Maximum temperature (molten solder temperature): 260°C
- Flow time: Within 10 seconds
- Preheat temperature (package surface temperature): Below 120°C
- Number of flows: 1
- Chlorine composition of rosin flux: 0.2% (wt.) or less

Partial Lead Heating (Hand Soldering)

- Maximum temperature (outer lead temperature): 260°C
- Time(per side of device*** or per lead***): Within 3 seconds
- Chlorine composition of rosin flux: 0.2% (wt.) or less

*** Time is defined per side for SMD and per lead for THD

Applicable packages: TFBGA, TSOPII

*Verification had been made to ensure that discrepancies did not occur with the mounting of devices under this reflow conditions. It is therefore required that devices be mounted in reflow profiles lying below this upper limit reflow conditions.